

SE3060D  
**N-Channel Enhancement-Mode MOSFET**

Revision: A

**General Description**

This type used advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of application

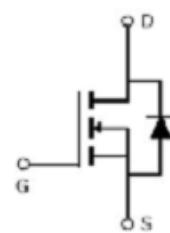
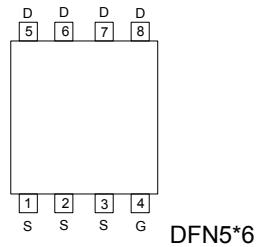
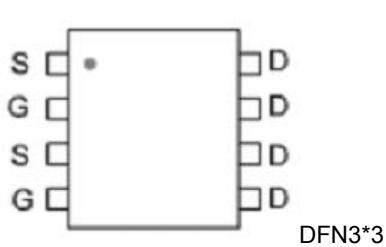
**Features**

For a single MOSFET

- $V_{DS} = 30V$
- $R_{DS(ON)} = 5.5m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} = 6m\Omega @ V_{GS}=5V$

**Pin configurations**

See Diagram below



**Absolute Maximum Ratings**

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	Continuous	$I_D$	A
	Pulsed		
Total Power Dissipation @ $T_A=25^\circ C$	$P_D$	53	W
Derating factor		0.56	W/ $^\circ C$
Single pulse avalanche energy	$E_{AS}$	306	mJ
Operating Junction Temperature Range	$T_J$	-55 to 175	$^\circ C$

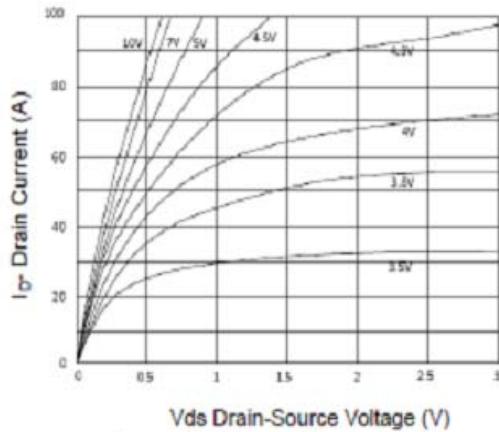
**Thermal Resistance**

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance Junction to Case	-	1.8	$^\circ C/W$

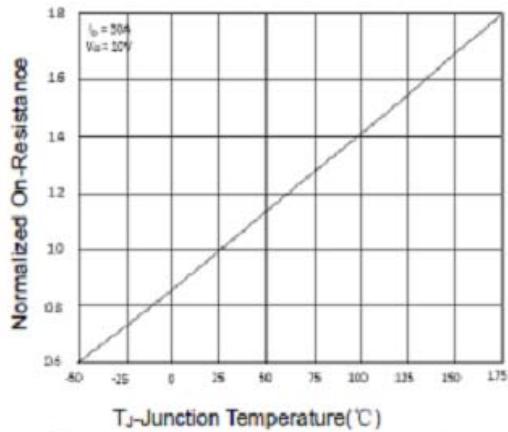
# SE3060D

Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS (Note 2)</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0 V	30			V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = 30V, V <sub>GS</sub> =0V			1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =20V			100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.6	3	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =25A	-	5.5	6.8	mΩ
		V <sub>GS</sub> =5V, I <sub>D</sub> =20A	-	6	9	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =24A	20			S
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		1595		pF
C <sub>oss</sub>	Output Capacitance			185		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			160		pF
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =15A		36		nC
Q <sub>gs</sub>	Gate Source Charge			6.2		nC
Q <sub>gd</sub>	Gate Drain Charge			7.5		nC
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>GEN</sub> =3.5Ω I <sub>D</sub> =10A		8		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			29		ns
t <sub>d(r)</sub>	Turn-On Rise Time			10.5		ns
t <sub>d(f)</sub>	Turn-Off Fall Time			9.5		ns
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =24A			1.2	V
I <sub>S</sub>	Diode Forward Current				80	A
t <sub>rr</sub>	Reverse Recovery Time	TJ=25°C, IF=80A Di/dt=100A/μs		32	50	nS
Q <sub>rr</sub>	Reverse Recovery Charge			12	20	nC
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible(turn-on is dominated by LS				

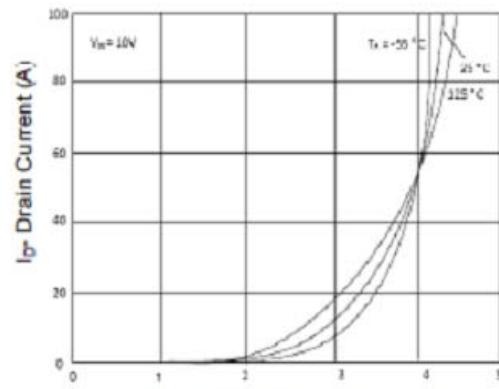
### Typical Characteristics



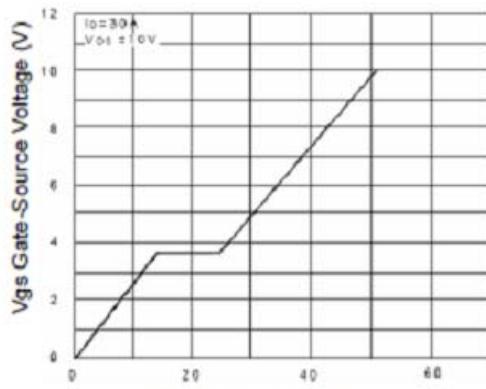
**Figure 1 Output Characteristics**



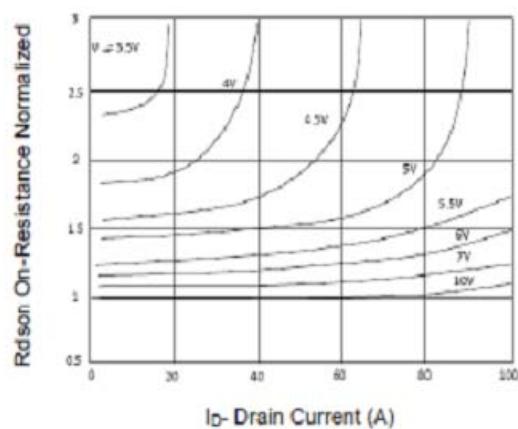
**Figure 4 Rdson-JunctionTemperature**



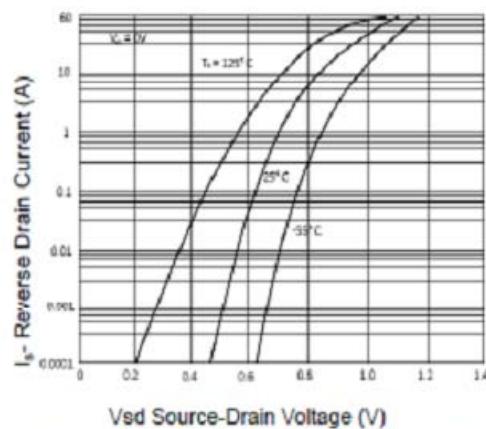
**Figure 2 Transfer Characteristics**



**Figure 5 Gate Charge**



**Figure 3 Rdson-Drain Current**



**Figure 6 Source-Drain Diode Forward**

### Typical Characteristics

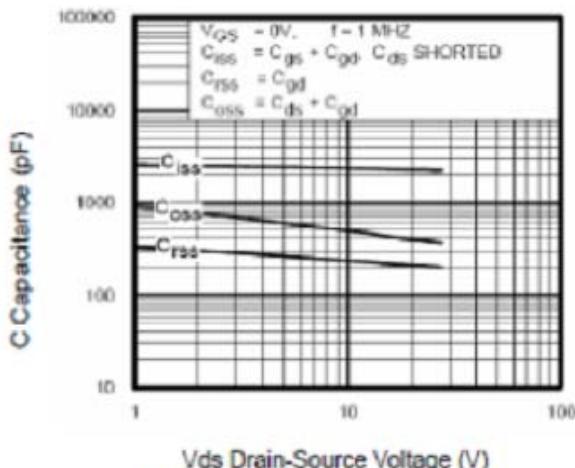


Figure 7 Capacitance vs Vds

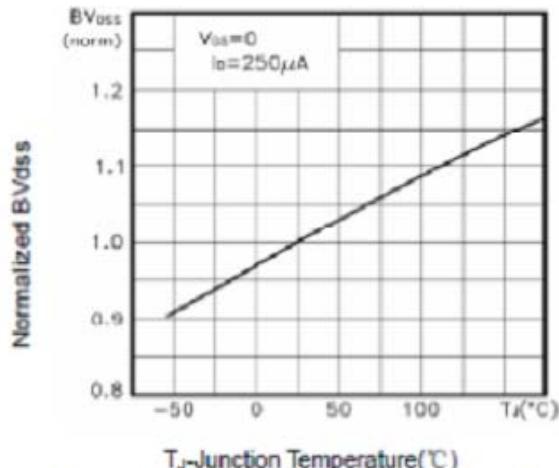


Figure 9 BV<sub>oss</sub> vs Junction Temperature

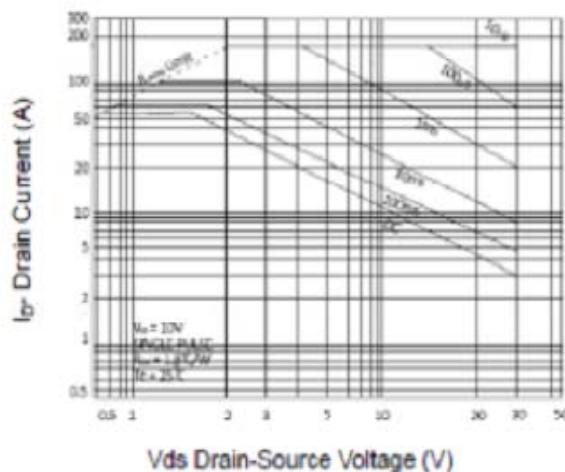


Figure 8 Safe Operation Area

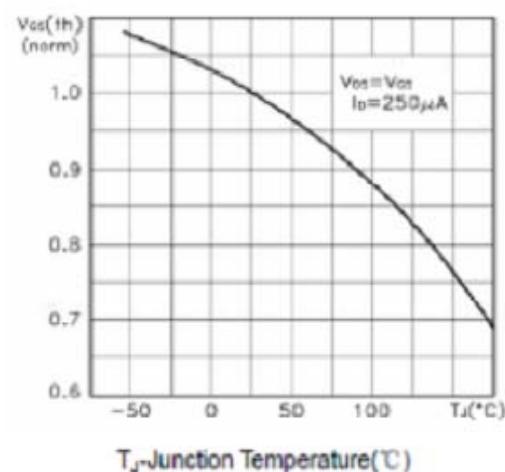


Figure 10 V<sub>Gs(th)</sub> vs Junction Temperature

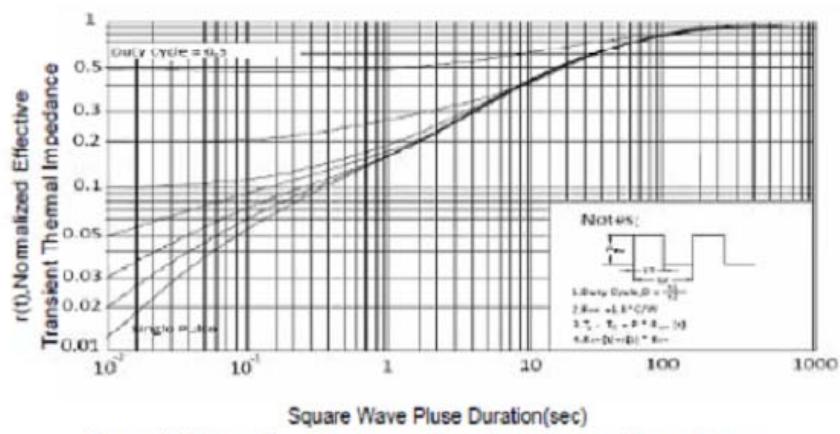
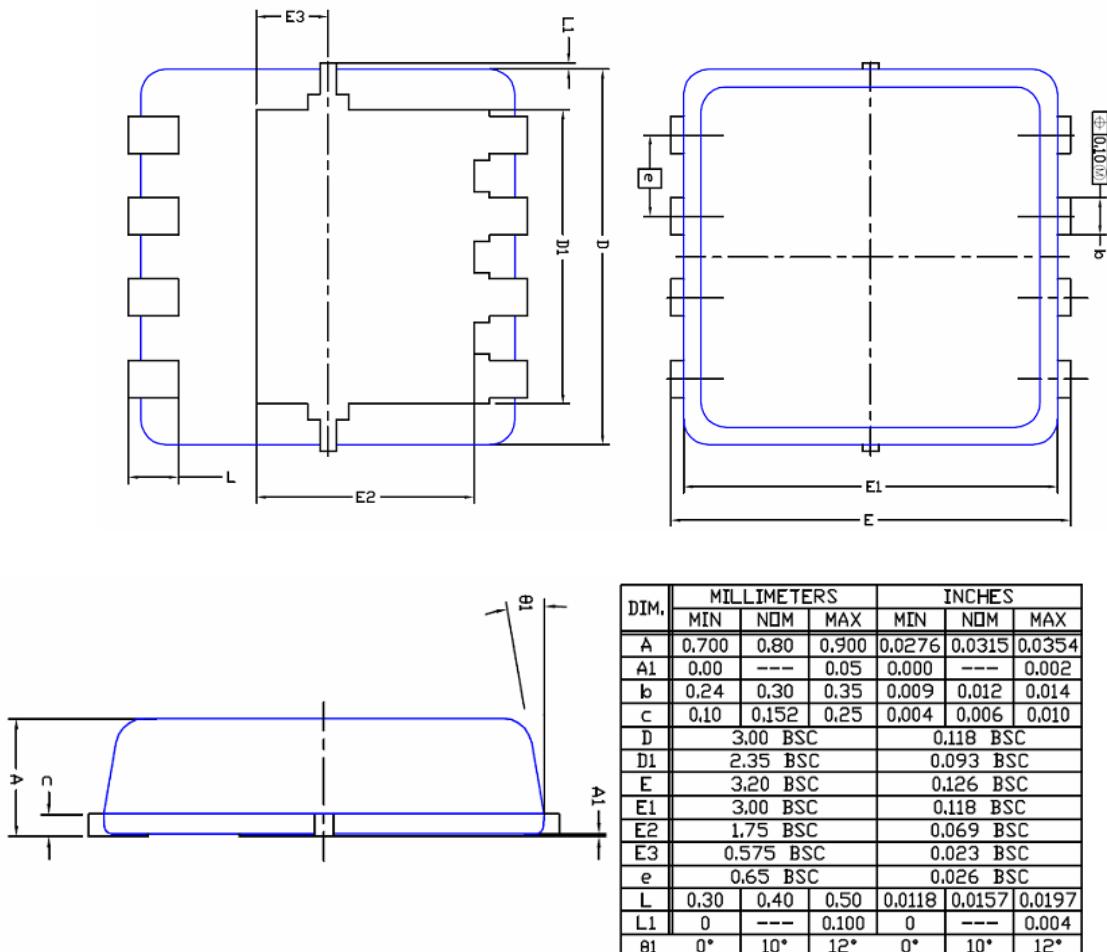


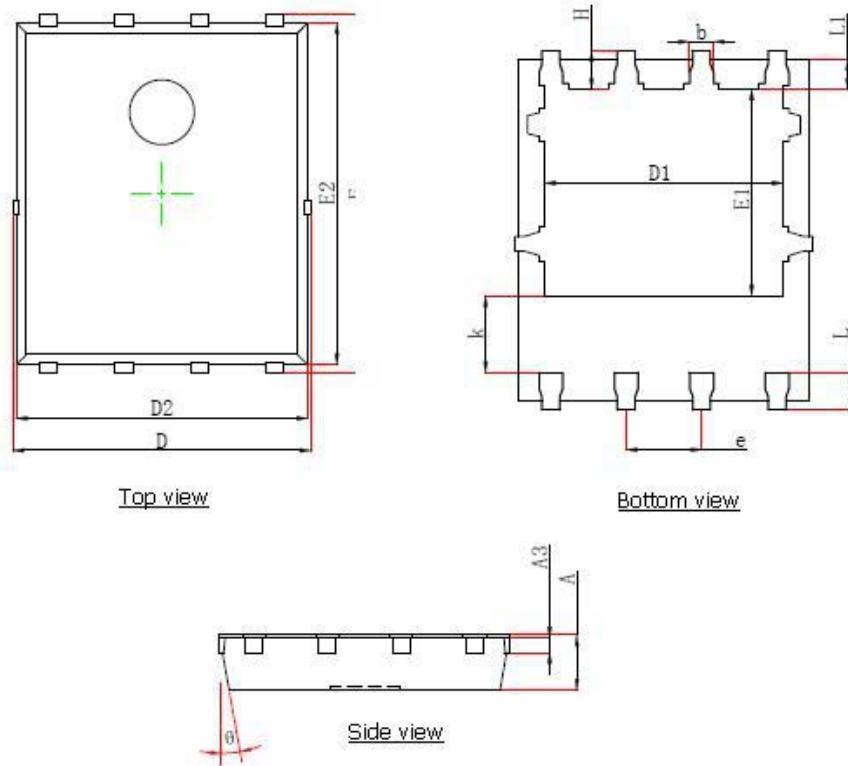
Figure 11 Normalized Maximum Transient Thermal Impedance

**SE3060D**

## Package Outline Dimension

DFN3X3



**Package Outline Dimension****DFN5X6**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
$\theta$	10°	12°	10°	12°

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